

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	3441391	(die chip ic (integrated adj circuit) semiconductor) dice	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/07 16:44
L2	504609	heat with (disipate dissipation dissipated sink metal spreader slug radiated radiating radiate)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/07 16:46
L3	25240	(mulitple plurality multi) with 2	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/07 16:48
L4	5086	3 same 1	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/07 16:48
L5	2107	(substrate board carrier pcb ((printed wiring circuit) adj4 board)) same 4	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/07 17:15
L6	1293	(package packaging packaging) and 5	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/01/07 17:16